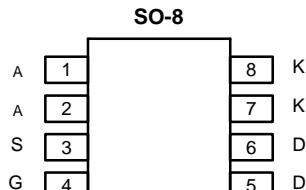


P-Channel 30-V (D-S) MOSFET with Schottky Diode

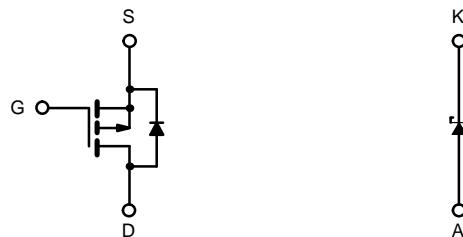
MOSFET PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-30	0.085 @ $V_{GS} = -10$ V	± 3.5
	0.180 @ $V_{GS} = -4.5$ V	± 2.5

SCHOTTKY PRODUCT SUMMARY		
V_{KA} (V)	V_F (V) Diode Forward Voltage	I_F (A)
30	0.5 V @ 1.0 A	1.4



Top View

LITTLE FOOT™ Plus



ABSOLUTE MAXIMUM RATINGS (T_A = 25°C UNLESS OTHERWISE NOTED)			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage (MOSFET)	V_{DS}	-30	V
Reverse Voltage (Schottky)	V_{KA}	30	
Gate-Source Voltage (MOSFET)	V_{GS}	± 20	
Continuous Drain Current (T _J = 150°C) (MOSFET) ^{a, b}	I_D	± 3.5	
T _A = 25°C		± 2.8	
Pulsed Drain Current (MOSFET)	I_{DM}	± 20	A
Continuous Source Current (MOSFET Diode Conduction) ^{a, b}	I_S	-1.7	
Average Forward Current (Schottky)	I_F	1.4	
Pulsed Forward Current (Schottky)	I_{FM}	30	
Maximum Power Dissipation (MOSFET) ^{a, b}	P_D	2	W
T _A = 70°C		1.3	
Maximum Power Dissipation (Schottky) ^{a, b}	P_D	1.9	
T _A = 70°C		1.2	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter	Device	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient (t ≤ 10 sec) ^a	MOSFET	R_{thJA}		62.5	°C/W
	Schottky			65	
Maximum Junction-to-Ambient (t = steady state) ^a	MOSFET		90		
	Schottky		92		

Notes

- a. Surface Mounted on FR4 Board.
- b. t ≤ 10 sec.

MOSFET SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

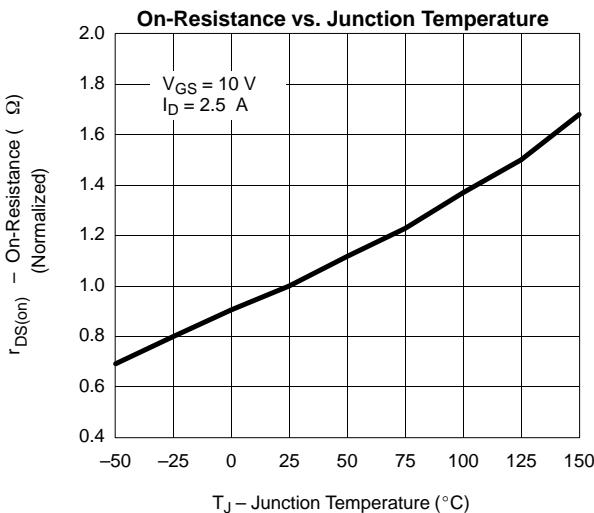
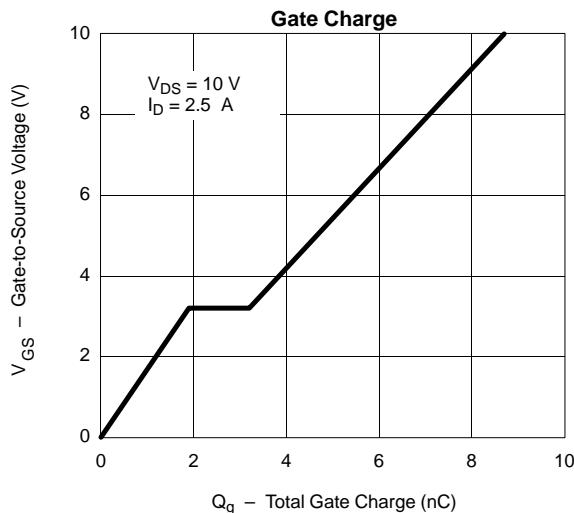
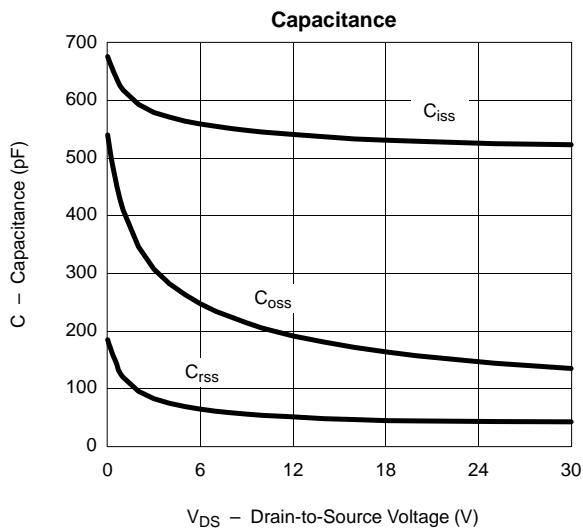
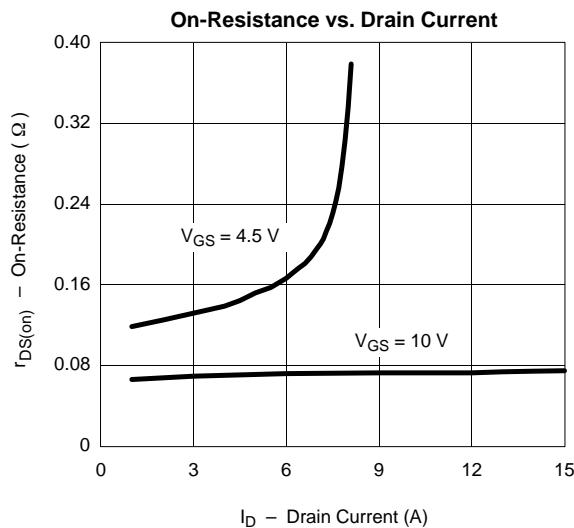
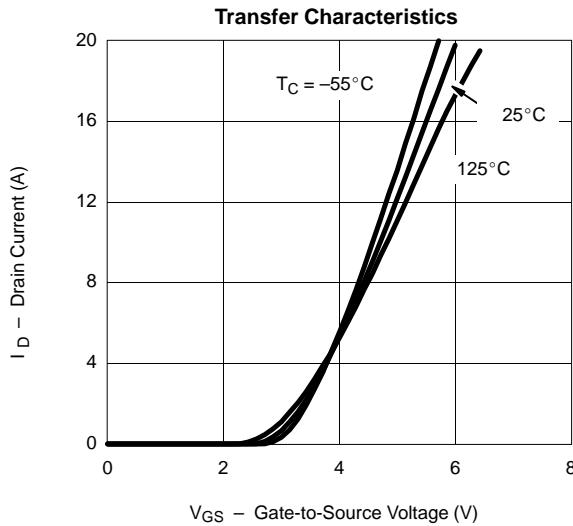
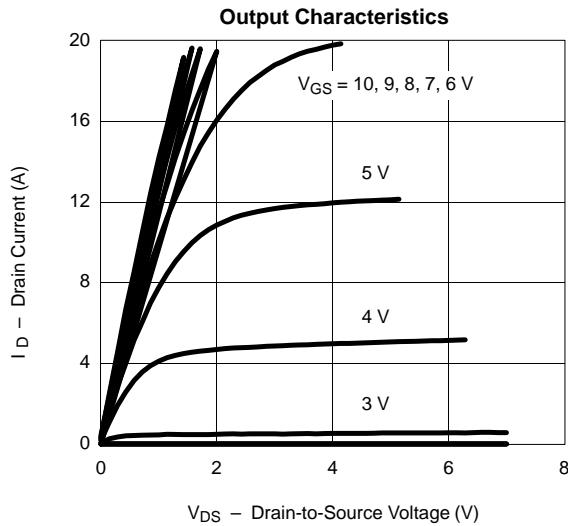
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	-1.0			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μA
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			-25	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq -5 \text{ V}, V_{GS} = -10 \text{ V}$	-15			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$		0.066	0.085	Ω
		$V_{GS} = -4.5 \text{ V}, I_D = -1.8 \text{ A}$		0.125	0.180	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.5 \text{ A}$		5.0		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -1.7 \text{ A}, V_{GS} = 0 \text{ V}$		-0.8	-1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -2.5 \text{ A}$		8.7	15	nC
Gate-Source Charge	Q_{gs}			1.9		
Gate-Drain Charge	Q_{gd}			1.3		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = -10 \text{ V}, R_L = 10 \Omega$ $I_D \approx -1 \text{ A}, V_{GEN} = -10 \text{ V}, R_G = 6 \Omega$		7	15	ns
Rise Time	t_r			9	18	
Turn-Off Delay Time	$t_{d(\text{off})}$			14	27	
Fall Time	t_f			8	15	
Source-Drain Reverse Recovery Time	t_{rr}		$I_F = -1.7 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	50	80	

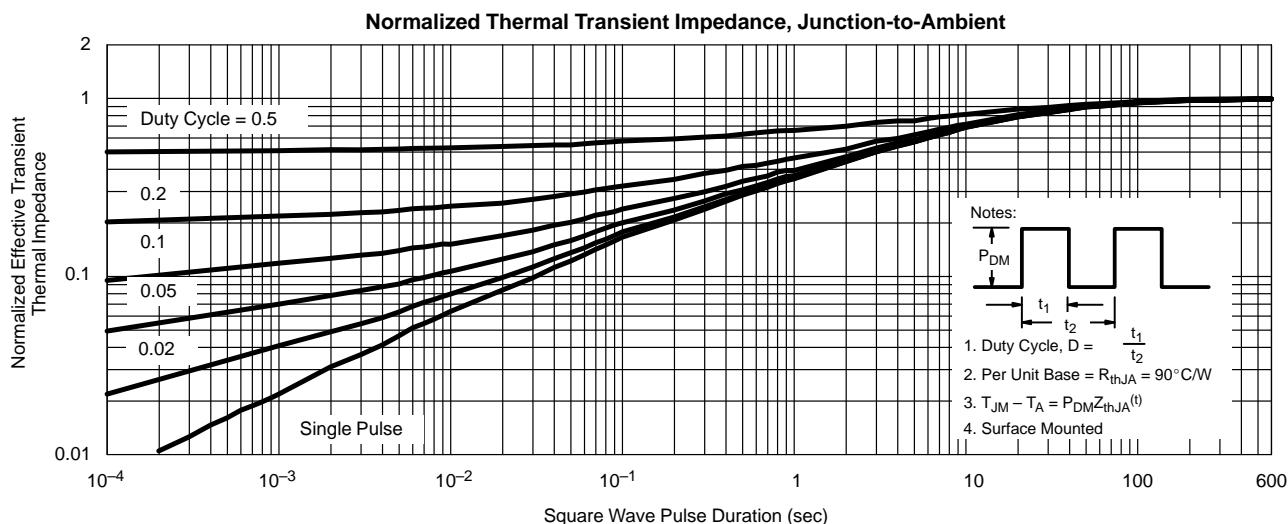
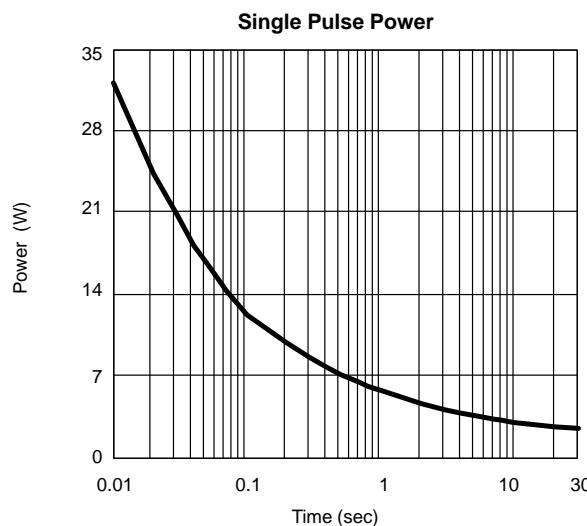
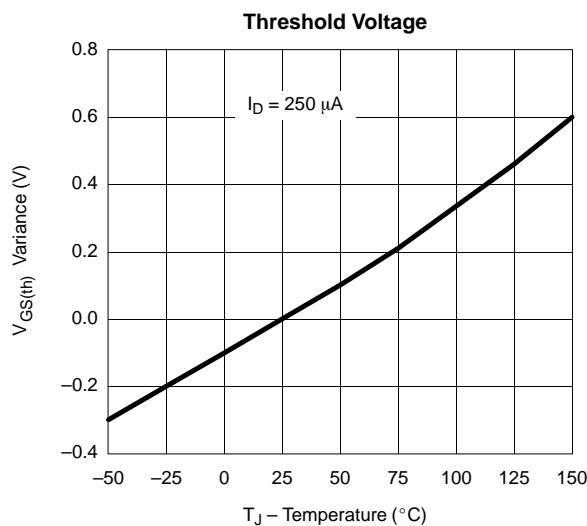
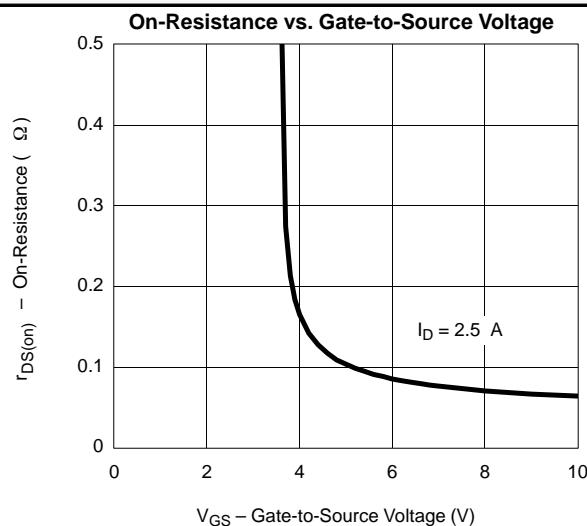
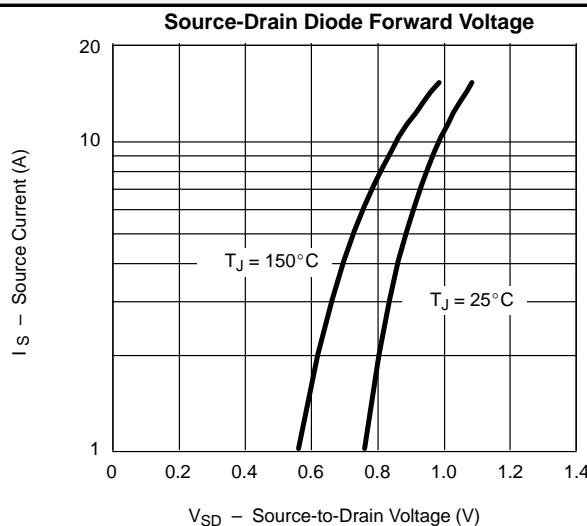
Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

SCHOTTKY SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage Drop	V_F	$I_F = 1.0 \text{ A}$		0.45	0.5	V
		$I_F = 1.0 \text{ A}, T_J = 125^\circ\text{C}$		0.36	0.42	
Maximum Reverse Leakage Current	I_{rm}	$V_r = 30 \text{ V}$		0.004	0.100	mA
		$V_r = 30 \text{ V}, T_J = 100^\circ\text{C}$		0.7	10	
		$V_r = -30 \text{ V}, T_J = 125^\circ\text{C}$		3.0	20	
Junction Capacitance	C_T	$V_r = 10 \text{ V}$		62		pF

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
MOSFET


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**MOSFET**

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
SCHOTTKY
